

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HZM6.8MFA

Silicon Planar Zener Diode for Surge Absorb



ADE-208-833A (Z)

Rev.1
Nov. 2001

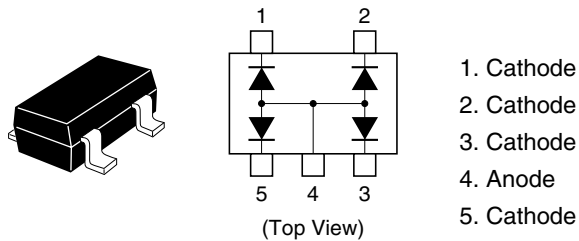
Features

- HZM6.8MFA has four devices in a monolithic, and can absorb surge.
- MPAK-5 Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HZM6.8MFA	68M	MPAK-5

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd *	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: Four device total, See Fig.2.

Electrical Characteristics*¹

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	V _z	6.47	—	7.00	V	I _z = 5 mA, 40 ms pulse
Reverse current	I _R	—	—	2	μA	V _R = 3.5 V
Capacitance	C	—	—	130	pF	V _R = 0 V, f = 1 MHz
Dynamic resistance	r _d	—	—	30	Ω	I _z = 5 mA
ESD-Capability * ²	—	30	—	—	kV	C = 150 pF, R = 330 Ω, Both forward and reverse direction 10 pulse

Notes: 1. Per one device.

2. Failure criterion ; I_R > 2 μA at V_R = 3.5 V.

Main Characteristic

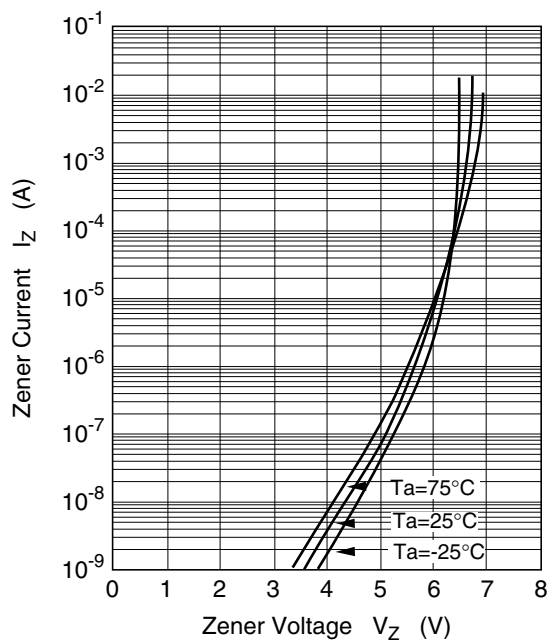


Fig.1 Zener current vs. Zener voltage

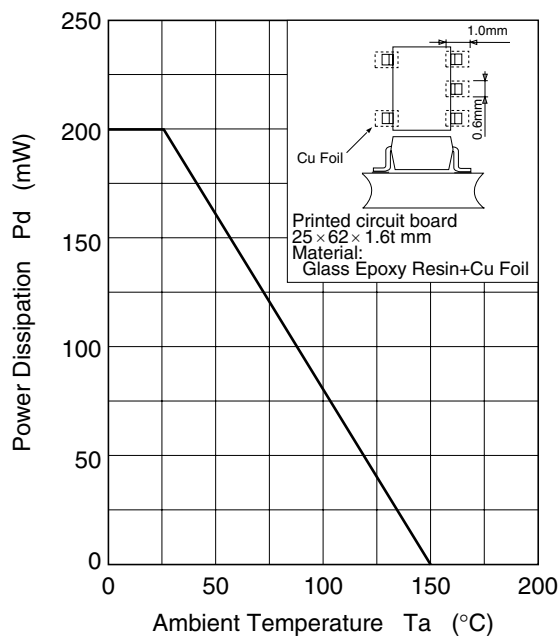
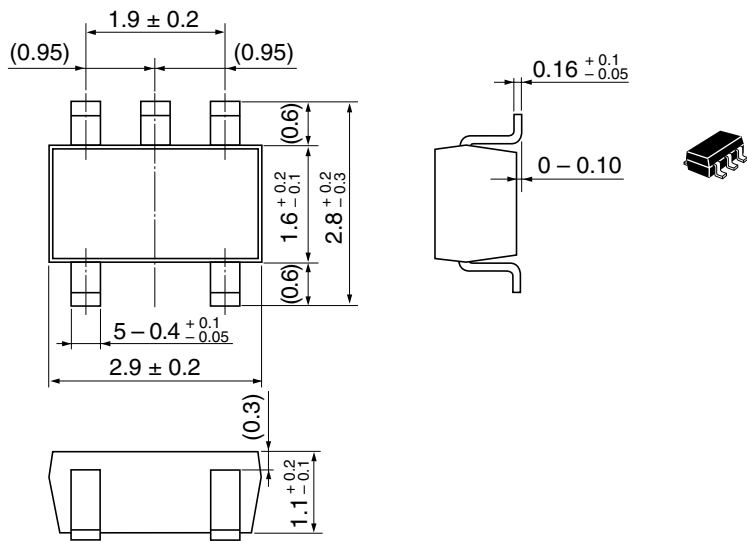


Fig.2 Power Dissipation vs. Ambient Temperature

Package Dimensions

As of July, 2001
Unit: mm



Hitachi Code	MPAK-5
JEDEC	—
JEITA	—
Mass (reference value)	0.013 g

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